

Announcements

EMPS 2006 - European Microelectronics and Packaging Symposium

22 - 24 May 2006
Terme Catez, Slovenia

The European Microelectronics and Packaging Symposium with Table-Top Exhibition, EMPS, is an international forum for presenting and discussing recent developments and future trends in the multidisciplinary field of microelectronics packaging and interconnection. The symposium, which is organised every two years in a different European country, combines both fundamental research and industrial applications and brings together specialists from industry and academia. The topics covered by the technical programme of the EMPS 2006 include all the important aspects of:

- **Materials & technologies**
- **Advanced packaging & MEMS**
- **Interconnection technologies & substrates**
- **Semiconductor structures and circuits**
- **Passive components, active devices & systems**
- **Electrical, thermal, mechanical and multi-physics simulations**
- **Microelectronic applications**
- **Quality & reliability**

Workshop

Prior to the symposium (May 21, 2006) a satellite Workshop on Ferroelectric Thin- & Thick-films Processing and Their Applications in MEMS will be organised by Jozef Stefan Institute in the frame of the Centre for Advanced Processing, Technologies and Materials for Ceramic Electro and Electromechanical Devices - SICER, (<http://dolomit.ijs.si/sicer>) at the same location. This is an excellent opportunity to take part in both events and to exchange your experiences with specialists in the field of ferroelectrics.

Contact:

EMPS 2006: info@emps2006.com

Workshop: barbara.malic@ijs.si

About (IMAP & MIDE)

IMAPS, The International Microelectronics and Packaging Society is the largest non-profit society for companies and institutions dedicated to the advancement and growth of the use of microelectronics and electronic packaging.

Founded in 1967, IMAPS is the largest international microelectronics and electronic packaging society with professional members in 24 North American chapters and 19 international chapters. Members of the Society represent every discipline and specialty in the electronics industry and include both technical and marketing professionals. Currently IMAPS has more than 7,000 members in the United States and more than 4,000 international members around the world.

The aim of the Society is the advancement and worldwide spread of knowledge and commercial realisation of microelectronics - a key technology in the assembly and application of silicon chip semiconductors, film circuits and printed wiring boards to form practical, miniaturised electronic equipment.

Society membership is open to all individuals connected with microelectronics; there are no formal educational qualification entry requirements, but professional skills and experience are recognised through adjudication and election to Senior and Fellow of the Society.

Society for Microelectronics, Electronic Components and Materials, MIDE, was founded in 1986 in Ljubljana, Slovenia. Although established locally, its membership base is international and includes professionals that work in the field of microelectronics, electronic components and materials.

Main activities of MIDE society are:

- Organisation of International Conference on Microelectronics, Devices and Materials. Already 41st conference will take place in 2005, please see more on www.midem-drustvo.si/conf2005
- Publishing of scientific Journal of Microelectronics, Electronic components and Materials - Informacije MIDE, ISSN 0352-9045.

MIDE'06 - 42nd International Conference on Microelectronics, Devices and Materials, with joint Workshop on MEMS and NEMS, Sept 13-15, 2006, Slovenia

General Information:

Organizers welcome you to the 42nd International Conference on Microelectronics, Devices and Materials, MIDE'06, together with the joint Workshop on MEMS and NEMS. This conference continues the tradition of annual international meetings organized by MIDE - Society for Microelectronics, Devices and Materials, Ljubljana, Slovenia. These conferences have always attracted a large number of Slovenian and foreign experts working in mentioned fields as well as many distinguished invited speakers. Therefore, once a year scientists and engineers have the opportunity to present their activities and research results to a broad audience and to discuss new trends and problems related to their fields. The official Conference language is English.

The conference will be held in the beautiful sea side resort at the Slovenian Adriatic coast. Looking forward to meet you in Slovenia!

Organizer:

MIDE - Society for Microelectronics, Electronic Components and Materials, Stegne 7, 1000 Ljubljana, SLOVENIA

Conference Sponsors:

Ministry of Education, Science and Technology of the Republic Slovenia

IMAPS, Slovenia Chapter

IEEE, Slovenia Section

MIDE'06 Conference - Topics:

Novel monolithic and hybrid circuit processing techniques, New device and circuit design, Thin films, Thick films, Process&Device modelling, Semiconductor physics, Sensors, Electromechanical devices, Microsystems, Optoelectronics, Photovoltaic devices, New materials and applications, Materials science and technology, Materials&Devices Characterization, Reliability and failure analysis, Education in the field of microelectronics, devices and materials.

Workshop on MEMS and NEMS - Topics:

Basic effects, New devices, Design, Technologies, Characterization, Applications.

Deadlines:

Abstract: June, 10, 2006

Notification of acceptance: June, 30, 2006

Organised by:

MIDE — Society for
Microelectronics, Electronic
Components and Materials —
IMAPS Slovenia Chapter
Stegne 7, SI-1000 Ljubljana
Slovenia
<http://www.midem-drustvo.si>